

**Amendments to the Claims**

Claims 1 – 6 (canceled)

Claim 7 (currently amended): An evaluation board for evaluating one or more aspects of a surface mount technology system, the board comprising:

- a) a substrate having a surface;
- b) a plurality of board pad patterns formed on the surface, wherein each of the board pad patterns includes a plurality of board pads; and ~~The evaluation board of claim 1,~~ wherein at least some of the board pad patterns are arranged in a matrix wherein the size of board pads in adjacent board pad patterns progressively changes.

Claim 8 (currently amended): An evaluation board for evaluating one or more aspects of a surface mount technology system, the board comprising:

- a) a substrate having a surface;
- b) a plurality of board pad patterns formed on the surface, wherein each of the board pad patterns includes a plurality of board pads; and ~~The evaluation board of claim 1,~~ wherein at least some of the board pad patterns are arranged in a matrix wherein the pad-to-pad spacing of board pads in adjacent board pad patterns progressively changes.

Claim 9 (original): The evaluation board of claim 7, wherein at least some of the board pad patterns are arranged in a matrix wherein the pad-to-pad spacing of board pads in adjacent board pad patterns progressively changes.

Claim 10 (currently amended): An evaluation board for evaluating one or more aspects of a surface mount technology system, the board comprising:

- a) a substrate having a surface;

b) a plurality of board pad patterns formed on the surface, wherein each of the board pad patterns includes a plurality of board pads; and ~~The evaluation board of claim 1,~~ wherein at least some of the board pads patterns are arranged in a two dimensional matrix having rows and columns of board pad patterns, and wherein in each row of the matrix, a first characteristic of the board pads in the board pad pattern is varied and wherein in each column of the matrix, a second characteristic of the board pads in the board pad patterns is varied.

Claim 11 (original): The evaluation board of claim 10, wherein the first characteristic is selected from the group consisting of: the shape; size; and pad-to-pad spacing of the board pads, and wherein the second characteristic is chosen from the group consisting of: the shape; size; and pad-to-pad spacing of the board pads, and wherein the first and second characteristics are different.

Claim 12 (currently amended): ~~The evaluation board of claim 1,~~ An evaluation board for evaluating one or more aspects of a surface mount technology system, the board comprising wherein the a substrate has having two surfaces, and wherein each surface has a plurality of board pad patterns formed on it, each board pad pattern comprising at least one board pad; wherein at least some of the board pad patterns are arranged in a matrix wherein at least one of the size and the pad-to-pad spacing of board pads in adjacent board pad patterns progressively changes.

Claim 13 (currently amended): The evaluation board of claim 12 ~~claim 1,~~ wherein ~~the substrate has two surfaces and~~ wherein the first surface has a plurality of board pad patterns formed of board pads and wherein the second surface has a plurality of area-filled board pads.

Claim 14 (currently amended): An evaluation board for evaluating one or more aspects of a surface mount technology system, the board comprising:

- (a) a substrate having a surface;
- (b) a plurality of board pad patterns formed on the surface, wherein each of the board pad patterns includes one of: an area-filled board pad or a plurality of board pads; wherein at least some of the board pad patterns are arranged in a matrix wherein at least one of the size and the pad-to-pad spacing of board pads in adjacent board pad patterns progressively changes.

Claims 15 – 16: (canceled)

Claim 17 (currently amended): An evaluation board for evaluating one or more aspects of a surface mount technology system, the board comprising:

- a) a substrate having a surface;
- b) a plurality of board pad patterns formed on the surface, wherein each of the board pad patterns includes an area-filled board pad; and ~~The evaluation board of claim 15,~~ wherein at least some of the board pad patterns are arranged in a matrix wherein the size of area-filled board pads in adjacent board pad patterns progressively changes.

Claim 18 (currently amended): An evaluation board for evaluating one or more aspects of a surface mount technology system, the board comprising:

- a) a substrate having a surface;
- b) a plurality of board pad patterns formed on the surface, wherein each of the board pad patterns includes an area-filled board pad; and ~~The evaluation board of claims 16,~~ wherein at least some of the board pad patterns are arranged in a matrix wherein the pad-to-pad spacing

of area-filled board pads in adjacent board pad patterns progressively changes.

Claim 19 (new): The evaluation board of claim 17, wherein at least some of the board pad patterns are arranged in a matrix wherein the pad-to-pad spacing of area-filled board pads in adjacent board pad patterns progressively changes.

Claim 20 (new): The evaluation board of claim 7, wherein in each of said board pad patterns, the board pads have a uniform shape, size and pad-to-pad spacing.

Claim 21 (new): The evaluation board of claim 8, wherein in each of said board pad patterns, the board pads have a uniform shape, size and pad-to-pad spacing.

Claim 22 (new): The evaluation board of claim 10, wherein in each of said board pad patterns, the board pads have a uniform shape, size and pad-to-pad spacing.

Claim 23 (new): The evaluation board of claim 14, wherein for each of the board pad patterns that includes a plurality of board pads, the board pads therein have a uniform shape, size and pad-to-pad spacing.

Claim 24 (new): The evaluation board of claim 12, wherein each of the two surfaces has a plurality of board pad patterns formed of board pads.

Claim 25 (new): The evaluation board of claim 12, wherein each of the two surfaces has a plurality of area-filled board pads.